



N-Channel 30-V (D-S) MOSFET with Schottky Diode

CHARACTERISTICS

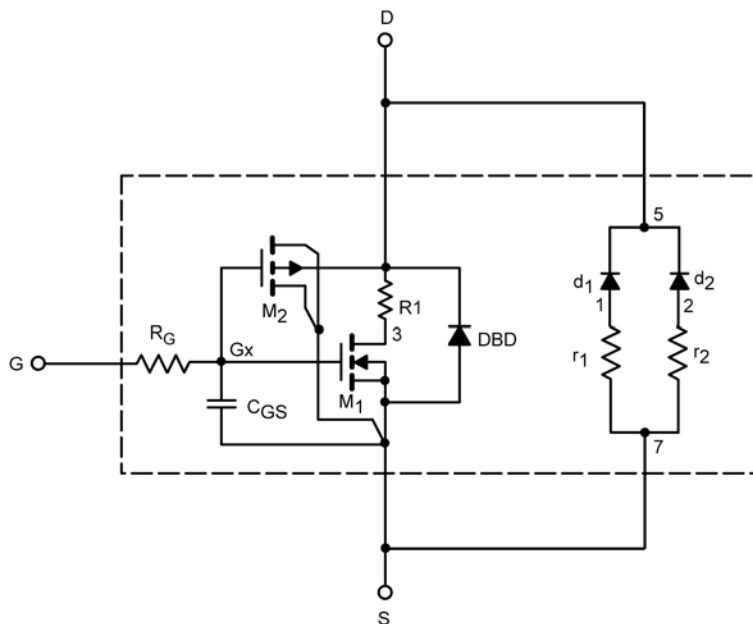
- N-Channel Vertical DMOS
- Macro Model (Subcircuit Model)
- Level 3 MOS
- Apply for both Linear and Switching Application
- Accurate over the -55 to 125°C Temperature Range
- Model the Gate Charge, Transient, and Diode Reverse Recovery Characteristics

DESCRIPTION

The attached spice model describes the typical electrical characteristics of the n-channel vertical DMOS. The subcircuit model is extracted and optimized over the -55 to 125°C temperature ranges under the pulsed 0-V to 10-V gate drive. The saturated output impedance is best fit at the gate bias near the threshold voltage.

A novel gate-to-drain feedback capacitance network is used to model the gate charge characteristics while avoiding convergence difficulties of the switched C_{gd} model. All model parameter values are optimized to provide a best fit to the measured electrical data and are not intended as an exact physical interpretation of the device.

SUBCIRCUIT MODEL SCHEMATIC



This document is intended as a SPICE modeling guideline and does not constitute a commercial product data sheet. Designers should refer to the appropriate data sheet of the same number for guaranteed specification limits.



| SPECIFICATIONS (T _J = 25°C UNLESS OTHERWISE NOTED) | | | | | |
|---|---------------------|---|----------------|---------------|------|
| Parameter | Symbol | Test Condition | Simulated Data | Measured Data | Unit |
| Static | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 1.9 | | V |
| Drain-Source On-State Resistance ^a | r _{DS(on)} | V _{GS} = 10V, I _D = 23.8A | 0.0047 | 0.0046 | Ω |
| | | V _{GS} = 4.5V, I _D = 21.8A | 0.0053 | 0.0055 | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 15V, I _D = 23.8A | 84 | 95 | S |
| Forward Voltage ^a | V _{SD} | I _F = 1A | 0.32 | 0.35 | V |
| Dynamic^b | | | | | |
| Input Capacitance | C _{iSS} | V _{DS} = 15V, V _{GS} = 10V, f = 1 MHz | 5453 | 5500 | pF |
| Output Capacitance | C _{oss} | | 855 | 870 | |
| Reverse Transfer Capacitance | C _{rss} | | 244 | 360 | |
| Total Gate Charge | Q _g | V _{DS} = 15V, V _{GS} = 10V, I _D = 20A | 77 | 81 | nC |
| | | | 38 | 38 | |
| Gate-Source Charge | Q _{gs} | V _{DS} = 15V, V _{GS} = 4.5V, I _D = 20A | 18 | 18 | |
| Gate-Drain Charge | Q _{gd} | | 11 | 11 | |

Notes

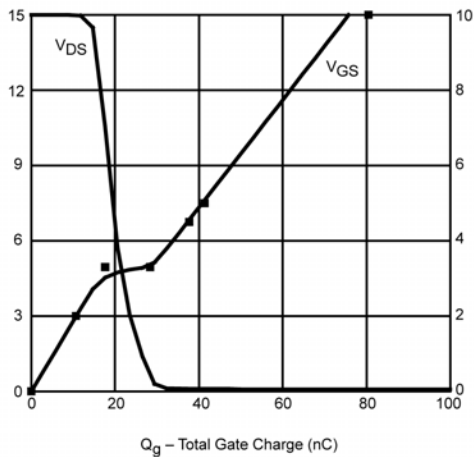
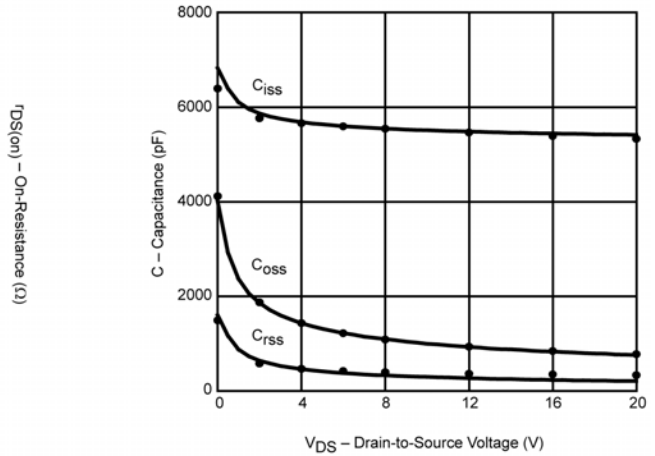
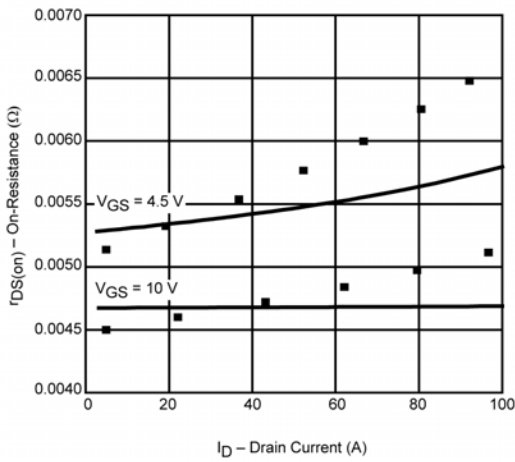
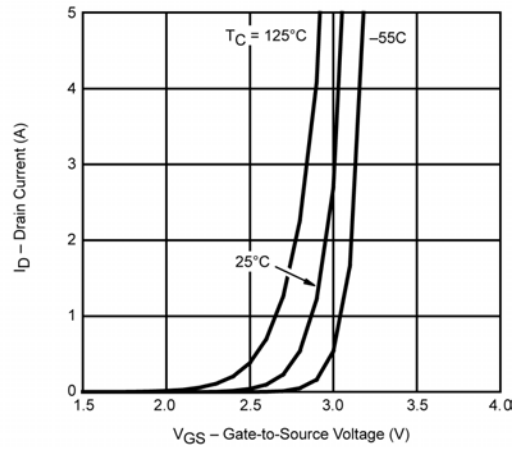
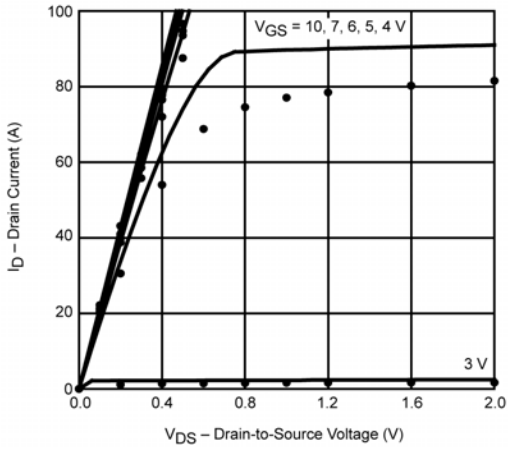
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.



SPICE Device Model Si7374DP

Vishay Siliconix

COMPARISON OF MODEL WITH MEASURED DATA ($T_J=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)



Note: Dots and squares represent measured data.



Disclaimer

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